

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD068N10N3 G	**Issued**	08. April 2022
MA#	MA005710822		
Package	PG-TO252-3-313	**Weight***	321.92 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.567	1.73	1.73	17294	17294
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		137	
	non noble metal	iron	7439-89-6	0.147	0.05		458	
	non noble metal	copper	7440-50-8	147.096	45.70	45.76	456930	457525
wire	non noble metal	aluminium	7429-90-5	5.564	1.73	1.73	17284	17284
encapsulation	inorganic material	zincoxide	1314-13-2	1.348	0.42		4188	
	miscellaneous	miscellaneous	-	6.741	2.09		20939	
	plastics	epoxy resin	-	20.222	6.28		62816	
	inorganic material	silicondioxide	60676-86-0	106.502	33.08	41.87	330831	418774
leadfinish	non noble metal	tin	7440-31-5	3.740	1.16	1.16	11618	11618
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4413	4424
solder	non noble metal	tin	7440-31-5	0.086	0.03		269	
	noble metal	silver	7440-22-4	0.108	0.03		336	
	non noble metal	lead	7439-92-1	4.129	1.28	1.34	12827	13432
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	5.96	5.97	59571	59649
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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